



THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4 / 105
5-28-03
exten

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: SEMICONDUCTOR PACKAGE DEVICE
Serial No.: 10/042,812 Filed: January 9, 2002
Examiner: Unknown Group Art Unit: 2811
Atty. Docket No.: BDG005

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

RECEIVED
APR 23 2003
TECHNOLOGY CENTER 2800

INFORMATION DISCLOSURE STATEMENT

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98, Applicant hereby provides a copy of the documents identified on the enclosed Form PTO-1449.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Accordingly, no fee is due. 37 C.F.R. § 1.97(b)(3).

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on April 15, 2003

 Sigmond

David M. Sigmond
Attorney for Applicant

4,15,03
Date of Signature

Respectfully submitted,

 Sigmond

David M. Sigmond
Attorney for Applicant
Reg. No. 34,013
(303) 554-8371
(303) 554-8667 (fax)